

Electronic Patent Application Fee Transmittal

Application Number:	10554855			
Filing Date:				
Title of Invention:	Brittle substrate cutting system and brittle substrate cutting method			
First Named Inventor/Applicant Name:	Kenji Otda			
Filer:	Howard I. Sobelman/Julie Eslick			
Attorney Docket Number:	49288.1600			
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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